

IN THE CLAIMS

This listing of claims will replace all prior versions, and
listings, of claims in the application:

Listing of Claims:

Claims 1-6 (Canceled)

7. (Original) An electronic device comprising a substrate with an electrical element on its first side which element comprises a first and a second electrode which are connected to a metallization by electrical contacts and electrodes of further electrical elements, the electronic device further comprising an inductive element, characterized in that the inductive element is defined in an electroconductive patterned layer which is located on the first side of the substrate and which is electroconductively connected to the metallization, isolating material being present between said substrate and the patterned layer in which isolating material the patterned layer has been mechanically embedded.

8. (Original) An electronic device as claimed in claim 7, characterized in that the patterned layer extends in a plane parallel to the first side beyond the substrate and contact pads for external contacting of the electronic device and the isolating material in essence completely envelops the substrate.

9. (Original) An electronic device as claimed in claim 7, characterized in that the patterned layer is situated between the isolating material and additional layers in which vertical interconnect areas (vias) are defined.

10. (Original) An electronic device as claimed in claim 7, characterized in that the metallization along a boundary face with the isolating material includes an inductive element which is situated substantially opposite the inductive element in the patterned layer, the inductive elements together forming a strip line.

11. (Original) An electronic device as claimed in claim 7,

characterized in that the substrate comprises a semiconductor material selected from the group of III-V and II-VI connectors and in that the electrical element is a semiconductor element.